

# WLCSP25\_5X5

wafer level chip-size package; 25 bumps (5 x 5)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP25
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-2-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
n <sub>2</sub>	actual quantity of termination	-	-	25	-	



## 2. Package outline

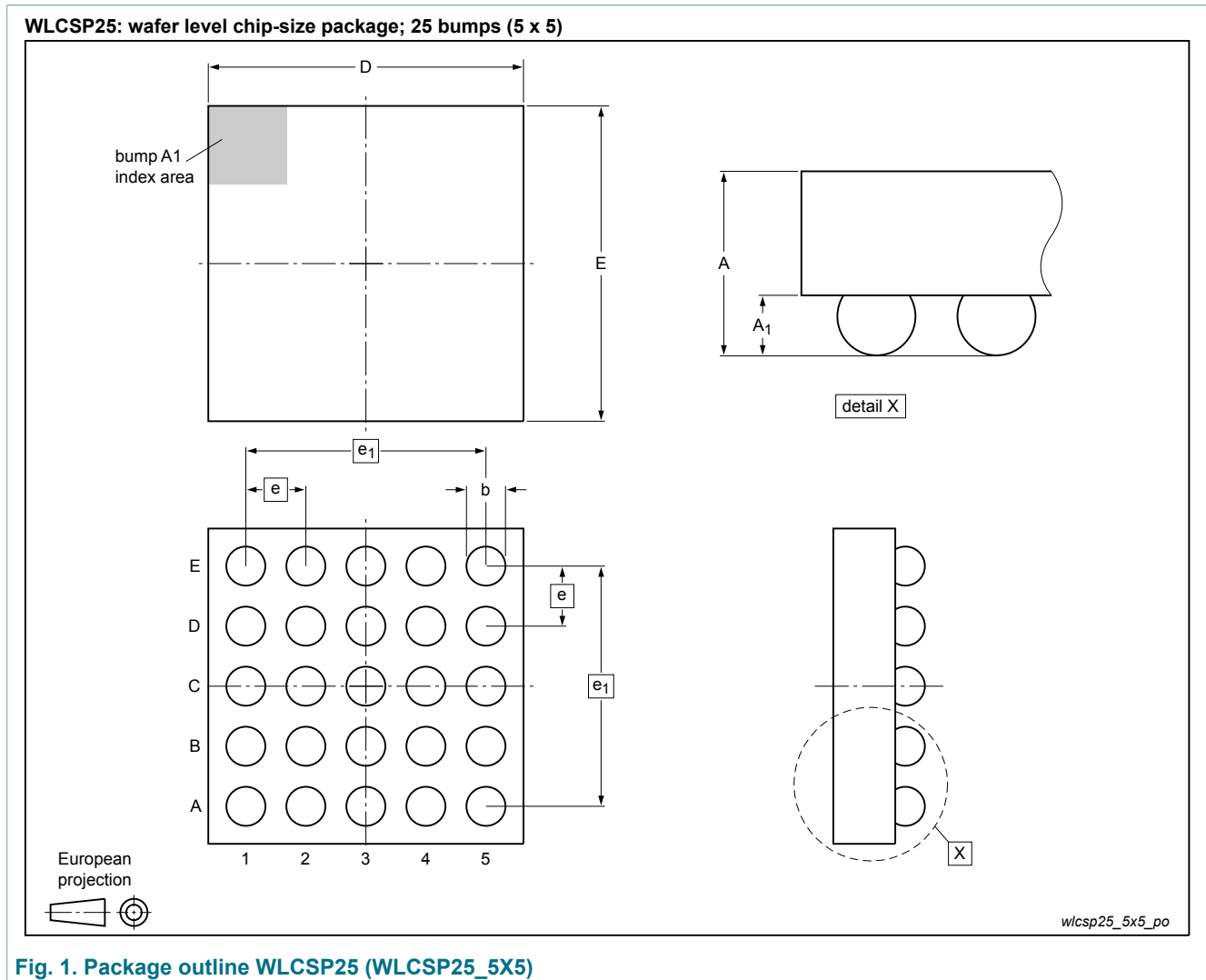


Fig. 1. Package outline WLCSP25 (WLCSP25\_5X5)

### 3. Legal information

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Date of release: 8 February 2016

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